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HEWLETT-PACKARD COMPANY
Intellectual Property Administration
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Cathi Christensen

(Depositor's name)

Cathi Christensen

(Signature)

9-20-2004

(Date)

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/992,864	11/16/2001	Jeffrey L. Deeney	10015589-1	5995

TITLE OF INVENTION: METHOD AND APPARATUS FOR SUPPORTING CIRCUIT COMPONENT HAVING SOLDER COLUMN ARRAY INTERCONNECTS USING INTERPOSED SUPPORT SHIMS

APPLN. TYPE	SMALL ENTITY	ISSUE FEE	PUBLICATION FEE	TOTAL FEE(S) DUE	DATE DUE
nonprovisional	NO	\$1330	\$300	\$1630	09/30/2004
EXAMINER	ART UNIT	CLASS-SUBCLASS			
BUI, HUNG S	2841	361-762000			

1. Change of correspondence address or indication of "Fee Address" (37 CFR 1.363).

☐ Change of correspondence address (or Change of Correspondence Address form PTO/SB/122) attached.☐ "Fee Address" indication (or "Fee Address" Indication form PTO/SB/47; Rev 03-02 or more recent) attached. Use of a Customer Number is required.

2. For printing on the patent front page, list (1) the names of up to 3 registered patent attorneys or agents OR, alternatively, (2) the name of a single firm (having as a member a registered attorney or agent) and the names of up to 2 registered patent attorneys or agents. If no name is listed, no name will be printed.

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3. ASSIGNEE NAME AND RESIDENCE DATA TO BE PRINTED ON THE PATENT (prior or type)

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(A) NAME OF ASSIGNEE

Hewlett-Packard Development Company, L.P.

(B) RESIDENCE: (CITY and STATE OR COUNTRY)

Houston, Texas

Please check the appropriate assignee category or categories (will not be printed on the patent);

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4a. The following fee(s) are enclosed:

☒ Issue Fee☒ Publication Fee☐ Advance Order - # of Copies _____

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(Authorized Signature)

(Date)

A. L. Christensen

SEPT. 20, 2004

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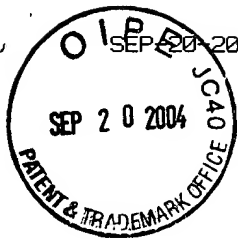
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FAX Coversheet

Date: 9-3-200420

No. Of Pages 3
Including Coversheet

TO: Mail Stop ISSUE FEE
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P O Box 1450
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FAX No.: 703 746 4000

FROM: Cathi Christensen

PHONE: 970-898-4403

RE: PDNO 10015588-1
ATTY AWW
S/N 09/992,864
FILING DATE 11/16/2001
INVENTOR Jeffrey L. Deeney
TITLE Method And Apparatus For Supporting Circuit Component Having Solder
Column Array Interconnects Using Interposed Support Shims

Please acknowledge receipt of the following documents for the above referenced Patent Application:

- Fee(s) Transmittal - In Duplicate